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FDBL0150N80

N-Channel PowerTrench[®] MOSFET 80 V, 300 A, 1.4 m Ω

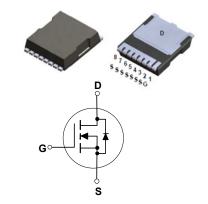
Features

- Typical $R_{DS(on)}$ = 1.1 mΩ at V_{GS} = 10V, I_D = 80 A
- Typical $Q_{q(tot)}$ = 172 nC at V_{GS} = 10V, I_D = 80 A
- UIS Capability
- RoHS Compliant

Applications

- Industrial Motor Drive
- Industrial Power Supply
- Industrial Automation
- Battery Operated tools
- Battery Protection
- Solar Inverters
- UPS and Energy Inverters
- Energy Storage
- Load Switch





July 2016

For current package drawing, please refer to the Fairchild website at https://www.fairchildsemi.com/evaluate/package-specifications/packageDetails.html?id=PN_PSOFA-008

MOSFET Maximum Ratings $T_J = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Ratings	Units	
V_{DSS}	Drain-to-Source Voltage		80	V
V_{GS}	Gate-to-Source Voltage		±20	V
	Drain Current - Continuous (V _{GS} =10) (Note 1)	T _C = 25°C	300	А
ID	Pulsed Drain Current	T _C = 25°C	See Figure 4	7
E _{AS}	Single Pulse Avalanche Energy	(Note 2)	820	mJ
D	Power Dissipation		429	W
P_{D}	Derate Above 25°C		2.86	W/°C
T _J , T _{STG}	Operating and Storage Temperature		-55 to + 175	°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case		0.35	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	(Note 3)	43	°C/W

Notes

- 1: Current is limited by bondwire configuration.
- 2: Starting T_J = 25°C, L = 0.4mH, I_{AS} = 64A, V_{DD} = 40V during inductor charging and V_{DD} = 0V during time in avalanche.

 3: R_{0,JA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder
- 3: R_{0,JA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{0,JC} is guaranteed by design, while R_{0,JA} is determined by the board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Package Marking and Ordering Information

Device Marking	Device	Package			
FDBL0150N80	FDBL0150N80	MO-299A	-	-	-

Units

Max.

Electrical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted.

Parameter

Off Ch	aracteristics						
B _{VDSS}	Drain-to-Source Breakdown Voltage	$I_D = 250 \mu A$	V _{GS} = 0V	80	-	-	V
I _{DSS}	Drain-to-Source Leakage Current	V _{DS} =80V,	$T_J = 25^{\circ}C$	-	-	1	μА
		$V_{GS} = 0V$	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	-	1	mA
I _{GSS}	Gate-to-Source Leakage Current	$V_{GS} = \pm 20V$	1	-	-	±100	nA

Test Conditions

Min.

Тур.

On Characteristics

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$		2.0	3.0	4.0	V
R _{DS(on)}	II)rain to Source ()n Resistance	I _D = 80A,	$T_{\rm J} = 25^{\rm o}{\rm C}$	-	1.1	1.4	mΩ
		V _{GS} = 10V	$T_J = 175^{\circ}C \text{ (Note 4)}$	-	2.4	3.1	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	-V _{DS} = 25V, V _{GS} = 0V, -f = 1MHz		-	12800	-	pF
C _{oss}	Output Capacitance			-	1925	-	pF
C _{rss}	Reverse Transfer Capacitance			-	139	-	pF
R_g	Gate Resistance	f = 1MHz		-	3.0	4.6	Ω
$Q_{g(ToT)}$	Total Gate Charge at 10V	$V_{GS} = 0$ to 10V	V _{DD} = 64V	-	172	188	nC
Q _{g(th)}	Threshold Gate Charge	V _{GS} = 0 to 2V I _D = 80A		-	23	27	nC
Q_{gs}	Gate-to-Source Gate Charge		_	-	51	-	nC
Q_{gd}	Gate-to-Drain "Miller" Charge			-	34	-	nC

Switching Characteristics

t _{on}	Turn-On Time	V_{DD} = 40V, I_{D} = 80A, V_{GS} = 10V, R_{GEN} = 6 Ω	-	-	128	ns
t _{d(on)}	Turn-On Delay		-	42	-	ns
t _r	Rise Time		-	73	-	ns
t _{d(off)}	Turn-Off Delay		-	87	-	ns
t _f	Fall Time		-	48	-	ns
t _{off}	Turn-Off Time		-	-	193	ns

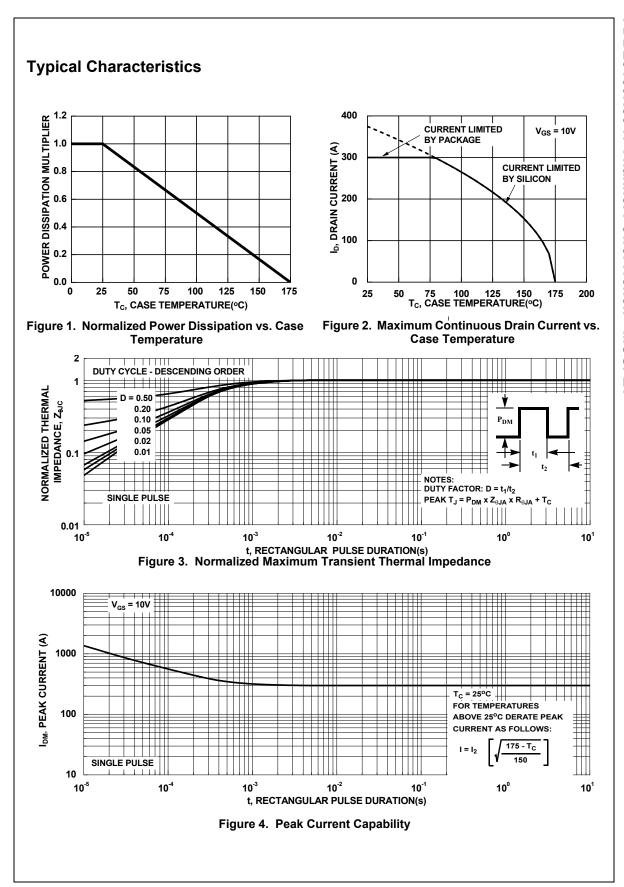
Drain-Source Diode Characteristics

V_{SD}	ISOURCE-TO-Drain Dione Voltage	I _{SD} =80A, V _{GS} = 0V	-	-	1.25	V
		I_{SD} = 40A, V_{GS} = 0V	-	-	1.2	V
t _{rr}	Reverse-Recovery Time	$I_F = 80A$, $dI_{SD}/dt = 100A/\mu s$,	-	117	136	ns
Q _{rr}	Reverse-Recovery Charge	$V_{DD}=64V$	-	205	269	nC

Note:

4: The maximum value is specified by design at T_J = 175°C. Product is not tested to this condition in production.

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Typical Characteristics

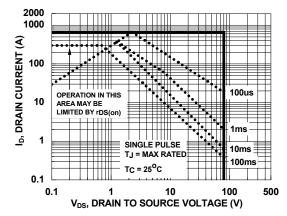
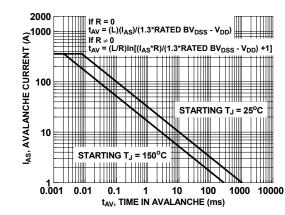


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to Fairchild Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching Capability

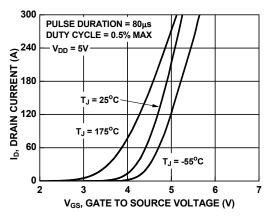


Figure 7. Transfer Characteristics

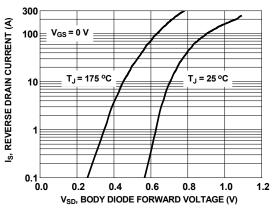


Figure 8. Forward Diode Characteristics

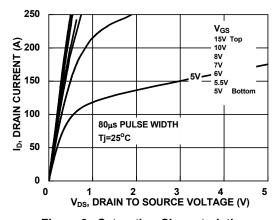


Figure 9. Saturation Characteristics

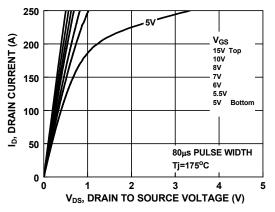


Figure 10. Saturation Characteristics

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Typical Characteristics

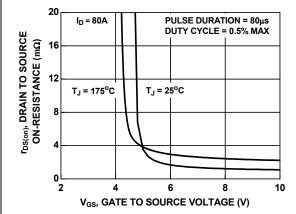


Figure 11. R_{DSON} vs. Gate Voltage

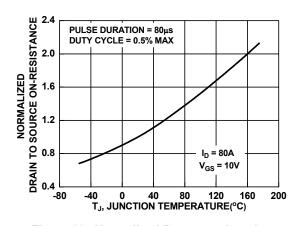


Figure 12. Normalized R_{DSON} vs. Junction Temperature

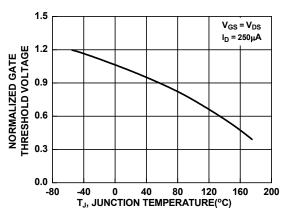


Figure 13. Normalized Gate Threshold Voltage vs. Temperature

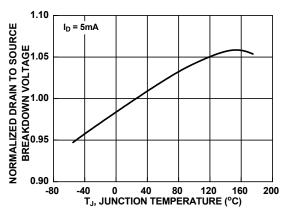


Figure 14. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

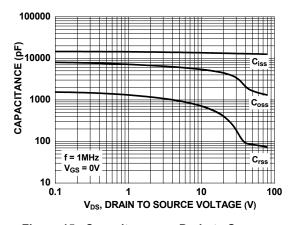


Figure 15. Capacitance vs. Drain to Source Voltage

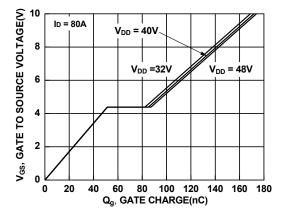
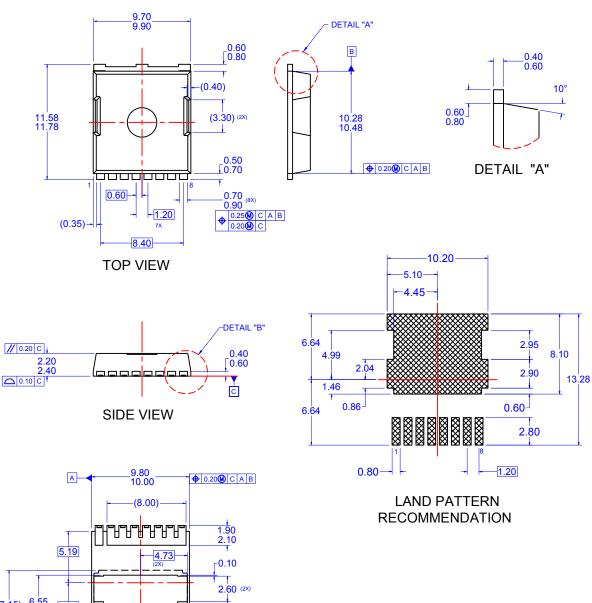


Figure 16. Gate Charge vs. Gate to Source Voltage

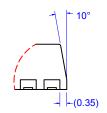
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NOTES: UNLESS OTHERWISE SPECIFIED

- A) PACKAGE STANDARD REFERENCE: JEDEC MO-299, ISSUE A, DATED NOVEMBER 2009.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- E) DRAWING FILE NAME: MKT-PSOF08AREV3

BOTTOM VIEW



DETAIL "B"

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